

East USP@USPT, W PID JPO

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1265145	pore or porous or foramin\$ or hole	US-PGPUB; USPAT	OR	ON	2005/11/09 21:29
L2	343524	mesh\$	US-PGPUB; USPAT	OR	ON	2005/11/09 21:29
L3	1735175	protect\$ or mask\$ or resist or photoresist or photomask or tape	US-PGPUB; USPAT	OR	ON	2005/11/09 21:29
L4	544567	grind\$ or lap\$ or cmp or \$polish\$ or chemimech\$ or abrad\$	US-PGPUB; USPAT	OR	ON	2005/11/09 21:29
L5	2423252	frontside\$ or backside\$ or front or back	US-PGPUB; USPAT	OR	ON	2005/11/09 21:29
L6	2883937	semiconduct\$ or wafer or chip or device	US-PGPUB; USPAT	OR	ON	2005/11/09 21:30
L7	96039	(1 or 2) with 3	US-PGPUB; USPAT	OR	ON	2005/11/09 21:06
L8	3648	7 same 4	US-PGPUB; USPAT	OR	ON	2005/11/09 21:06
L9	1192	6 same 8	US-PGPUB; USPAT	OR	ON	2005/11/09 21:07
L10	372103	3 with 6	US-PGPUB; USPAT	OR	ON	2005/11/09 21:07
L11	130839	3 with 5	US-PGPUB; USPAT	OR	ON	2005/11/09 21:08
L12	721	9 same (10 or 11)	US-PGPUB; USPAT	OR	ON	2005/11/09 21:08
L13	21166	3 with 5 with 6	US-PGPUB; USPAT	OR	ON	2005/11/09 21:09
L14	143	12 same 13	US-PGPUB; USPAT	OR	ON	2005/11/09 21:10
L15	1468996	pore or porous or foramin\$ or hole	JPO; DERWENT	OR	ON	2005/11/09 21:29
L16	151792	mesh\$	JPO; DERWENT	OR	ON	2005/11/09 21:29
L17	1377221	protect\$ or mask\$ or resist or photoresist or photomask or tape	JPO; DERWENT	OR	ON	2005/11/09 21:29
L18	330138	grind\$ or lap\$ or cmp or \$polish\$ or chemimech\$ or abrad\$	JPO; DERWENT	OR	ON	2005/11/09 21:29
L19	1519800	frontside\$ or backside\$ or front or back	JPO; DERWENT	OR	ON	2005/11/09 21:29
L20	5656420	semiconduct\$ or wafer or chip or device	JPO; DERWENT	OR	ON	2005/11/09 21:30
L21	59275	(15 or 16) with 17	JPO; DERWENT	OR	ON	2005/11/09 21:30
L22	635	18 and (19 or 20) and 21	JPO; DERWENT	OR	ON	2005/11/09 21:55

L23	73243	18 with (19 or 20)	JPO; DERWENT	OR	ON	2005/11/09 21:31
L24	318	22 and 23	JPO; DERWENT	OR	ON	2005/11/09 21:32
L25	296568	17 with (19 or 20)	JPO; DERWENT	OR	ON	2005/11/09 21:32
L26	224	24 and 25	JPO; DERWENT	OR	ON	2005/11/09 21:33
L27	129	24 and 25	DERWENT	OR	ON	2005/11/09 21:51
L28	0	26 not 27	DERWENT	OR	ON	2005/11/09 21:51
L29	52	24 not 27	DERWENT	OR	ON	2005/11/09 21:51
L30	188	22 not 24	DERWENT	OR	ON	2005/11/09 21:56

STN Columbus, Japio

(FILE 'HOME' ENTERED AT 17:23:36 ON 09 NOV 2005)

FILE 'CPLUS' ENTERED AT 17:23:44 ON 09 NOV 2005

L1 616661 S PORE OR PORES OR HOLE OR HOLES OR POROUS OR OPENINGS
L2 86685 S MESH?
L3 3661 S FORAMIN?
L4 730376 S PROTECT? OR MASK? OR RESIST OR PHOTORESIST OR PHOTOMASK?
L5 54752 S TAPE OR TAPES
L6 212935 S GRIND? OR LAP? OR ABRAD? OR CMP OR ?POLISH? OR CHEMIMECH?
L7 548 S FORAMINOUS
L8 1120127 S WAFER? OR SEMICONDUCT? OR CHIP? OR DEVICE
L9 119084 S FRONT?
L10 482200 S BACK?
L11 12419 S (L1 OR L2 OR L3) (10A) (L4 OR L5)
L12 43128 S (L4 OR L5) (10A) L8
L13 812 S L12 (10A) (L9 OR L10)
L14 50 S L11 AND L13

FILE 'JAPIO' ENTERED AT 17:28:55 ON 09 NOV 2005

L15 65 S L14

FILE 'USPAT2' ENTERED AT 17:29:47 ON 09 NOV 2005

L16 135 S L11 (P) L13
L17 37 S L16 (P) (CUT? OR SLICE? OR CHIPS? OR SEPARATE? OR SCRIBE? OR LA
L18 72 S L11 (15A) L13
L19 60 S L18 NOT L17